

PCN Number:	20130913002			PCN Date:	09/17/2013
Title:	TL331-Q1 data sheet - CMS C1308059				
Customer Contact:	PCN Manager	Phone:	+1(214) 480-6037	Dept:	Quality Services
Change Type:					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input checked="" type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
	<input type="checkbox"/>		Part number change		
PCN Details					
Description of Change:					
<p>Texas Instruments publication SLVS969 has changed as described below:</p> <p>Page 3 Added a Thermal Information table Page 3 Changed VICR in the Electrical Characteristics table Page 3 Changed test conditions of IOL in the Electrical Characteristics table</p>					
Reason for Change:					
Correct the test conditions.					
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):					
No anticipated impact. This is a specification change announcement only. There is no change to the actual device.					
Changes to product identification resulting from this PCN:					
None.					
Product Affected:					
TL331QDBVRQ1 TL331IDBVRQ1					

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com